

## Product Change Notification - KSRA-20KRVB706

**Date:** 23 Mar 2017  
**Product Category:** Memory; Sigma - Delta A/D Converters; 8-bit PIC Microcontrollers  
**Notification subject:** CCB 2845: Initial Notice: Qualification of ASSH as an additional assembly site for selected products of 160K wafer technology available in 8L SOIC package using CuPdAu bond wire  
**Notification text:** **PCN Status:**  
 Initial notification.

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of ASSH as an additional assembly site for selected products of 160K wafer technology available in 8L SOIC package using palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre Change:**

Assembled at ANAP and NSEB Assembly site

**Post Change:**

Assembled at ANAP, NSEB and ASSH Assembly site

**Pre and Post Change Summary:**

	Pre Change		Post Change		
	ANAP	NSEB	ANAP	NSEB	ASSH
<b>Assembly Site</b>	ANAP	NSEB	ANAP	NSEB	ASSH
<b>Wire material</b>	Au Wire	Au Wire	Au Wire	Au Wire	CuPdAu Wire
<b>Die attach material</b>	8290	2200D	8290	2200D	EN4900G
<b>Molding compound material</b>	G600	G600	G600	G600	CEL-9240HF10AK
<b>Lead frame material</b>	C194	C194	C194	C194	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying ASSH assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

May 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been

issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	March 2017					-->	May 2017				
Workweek	09	10	11	12	13		18	19	20	21	22
Initial PCN Issue Date				X							
Qual Report Availability							X				
Final PCN Issue Date							X				

**Method to Identify Change:**  
Traceability code

**Qualification Plan:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**  
**March 23, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_KSRA-20KRVB706\\_Affected CPN.pdf](#)
  - [PCN\\_KSRA-20KRVB706\\_Qual Plan.pdf](#)
  - [PCN\\_KSRA-20KRVB706\\_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Number (CPN)

<b>PCN_KSRA-20KRVB706</b>
<b>Catalog Part Number</b>
24AA128-I/SN
24AA128T-I/SN
24AA128T-I/SNRVF
24FC128-E/SN
24FC128-I/SN
24FC128T-E/SN
24FC128T-I/SN
24FC256-E/SN
24FC256-I/SN
24FC256T-E/SN
24FC256T-I/SN
25AA320A-I/SN
25AA320A-I/SNB22
25AA320AT-I/SN
25AA320AT-I/SNB22
25AA640A-E/SN
25AA640A-I/SN
25AA640AT-E/SN
25AA640AT-I/SN
25AA640AT-I/SNB23
25LC320A-E/SN
25LC320A-I/SN
25LC320AT-E/SN
25LC320AT-I/SN
25LC640A-E/SN
25LC640A-I/SN
25LC640AT-E/SN
25LC640AT-I/SN
MCP3550-50E/SN
MCP3550-60E/SN
MCP3550T-50E/SN
MCP3550T-60E/SN
MCP3551-E/SN
MCP3551T-E/SN
MCP3553-E/SN
MCP3553T-E/SN
PIC12F635-E/SN
PIC12F635-I/SN
PIC12F635-I/SN057
PIC12F635T-I/SN
PIC12F635T-I/SN037
PIC12F635T-I/SN041
PIC12F635T-I/SN043

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Affected Catalog Part Number (CPN)

<b>PCN_KSRA-20KRVB706</b>
<b>Catalog Part Number</b>
PIC12F635T-I/SN046
PIC12F635T-I/SN047
PIC12F635T-I/SN050
PIC12F635T-I/SN058
PIC12F635T-I/SN066
PIC12F683-E/SN
PIC12F683-E/SN083
PIC12F683-E/SN084
PIC12F683-I/SN
PIC12F683-I/SN075
PIC12F683-I/SNAU
PIC12F683T-E/SN
PIC12F683T-E/SN029
PIC12F683T-E/SN030
PIC12F683T-E/SN035
PIC12F683T-E/SN040
PIC12F683T-E/SN042
PIC12F683T-E/SN077
PIC12F683T-E/SN079
PIC12F683T-E/SN083
PIC12F683T-E/SN084
PIC12F683T-E/SN092
PIC12F683T-E/SN097
PIC12F683T-E/SN098
PIC12F683T-I/SN
PIC12F683T-I/SN061
PIC12F683T-I/SN062
PIC12F683T-I/SN072
PIC12F683T-I/SN091
PIC12F683T-I/SNAU
PIC12F683-E/SN083
PIC12F683-E/SN084
PIC12F683-I/SN
PIC12F683-I/SN075
PIC12F683-I/SNAU
PIC12F683T-E/SN
PIC12F683T-E/SN029
PIC12F683T-E/SN030
PIC12F683T-E/SN035
PIC12F683T-E/SN040
PIC12F683T-E/SN042
PIC12F683T-E/SN077
PIC12F683T-E/SN079

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Affected Catalog Part Number (CPN)

<b>PCN_KSRA-20KRVB706</b>
<b>Catalog Part Number</b>
PIC12F683T-E/SN083
PIC12F683T-E/SN084
PIC12F683T-E/SN092
PIC12F683T-E/SN097
PIC12F683T-E/SN098
PIC12F683T-I/SN
PIC12F683T-I/SN061
PIC12F683T-I/SN062
PIC12F683T-I/SN072
PIC12F683T-I/SN091
PIC12F683T-I/SNAU